LISTING OF THE CLAIMS:

Claim 1 (Currently Amended) A laminate support used in the process of for wire bonding a circuit

device in large scale integrated circuitry, in which is said circuit device comprises a circuit pad

arranged on a substrate, comprising:

said substrate being a closed woven mesh structure having a first surface supporting said circuit

device; and

a wire having a diameter being positioned on said first surface of said substrate, said closed woven

mesh structure of the substrate including a closed woven mesh having a thickness of between about

2.5 and 4.0 mils and being constituted of fiberglass having strands whose possessing separation

distance is distances which are equal to or less than said-diameter a cross-sectional diameter of said

wire positioned on said first surface of said substrate, said separation distance distances between said

strands being within the range of about 0.2 to 0.7 mils so as to substantially prevent deformation and

collapse of said circuit device during said process of in response to wire bonding.

Claims 2-5 (Cancelled).

Claim 6 (Currently Amended) The laminate support used in the process of wire bonding a circuit

device in accordance with claim 1, wherein said circuit device is a comprises said circuit pad of large

scale integrated design.

2

G:\IBM\1110\18194\Amend\18194.amd5.doc

Claim 7 (Currently Amended) A <u>The</u> laminate support used in the process of wire bonding a circuit device which is arranged on a substrate, comprising: in accordance with claim 1, wherein:

said substrate having a first surface supporting said circuit device; and

a wire having a thickness positioned on said first surface of said substrate, said closed woven mesh structure of said substrate including a closed woven mesh having a thickness of between about 2.5 to 4.0 mils and being is constituted of fiberglass having warp and weave strands, whose separation distance is distances are equal to or less than the thickness of said wire on said first surface of said substrate, as measured lengthwise through said closed woven mesh, said separation distance of said strands being within the range of about 0.2 to 0.7 mils so as to substantially prevent deformation and collapse of said circuit device during said process of wire bonding.

Claims 8-11 (Cancelled).

Claim 12 (Cancelled).

G:\IBM\1110\18194\Amend\18194.amd5.doc